

Please amend the section entitled "Brief Description of the Drawings" beginning on page 2, line 21 through page 3, line 15 as follows:

Brief Description of the Drawings

Figure 1 is an exploded perspective view of a thermal solution attachment mechanism in one embodiment of the present invention.

Figure 2 is a plan view of a backing plate in the thermal solution attachment mechanism of Figure 1 in one embodiment of the present invention.

Figure 3A is a plan view of a locking post in the thermal solution attachment mechanism of Figure 1 in one embodiment of the present invention.

Figure 3B is a plan view of an alternative locking post in one embodiment of the present invention.

Figure 3C is a plan view of another alternative locking post in one embodiment of the present invention.

Figure 4 is a plan view of a mounting plate having slots in the thermal solution attachment mechanism of Figure 1 in one embodiment of the present invention.

Figure 5A is a cut-away perspective view of the slots in the mounting plate of Figure 4 in one embodiment of the present invention.

Figure 5B is a cut-away perspective view of alternative slots in an alternative mounting plate in one embodiment of the present invention.

Figures 6A-6E are schematic illustrations showing a sequence of assembly steps for assembling the thermal solution attachment mechanism of Figure 1 and securing a thermal solution thereon in one embodiment of the present invention.

Figure 7 is a block diagram of various methods for securing a thermal solution attachment mechanism to a circuit board in one embodiment of the present invention.

Figure 8 is a block diagram of a method for temporarily attaching a thermal solution to a processor in one embodiment of the present invention.

Figure 9 is an exploded perspective view of an alternative thermal solution attachment mechanism in one embodiment of the present invention.